

ABSTRACT

A package structure which aims at improvement in function, miniaturization, and systematization of a semiconductor integrated circuit having been made into multichip is offered.

A substrate in which a plurality of terminals for a test and a plurality of terminals for external connection are arranged on the front surface, and a plurality of terminals for internal connection are arranged on the back surface, and a semiconductor chip in which a plurality of surface terminals connected to an internal circuit are formed in the front surface are prepared. An encapsulated semiconductor package is formed by joining the back surface of this semiconductor chip to the back surface of the substrate, connecting the surface terminal of the semiconductor chip to the desired terminal for internal connection of the substrate, and sealing the semiconductor chip on the back surface of the substrate with a molded member. A multichip structure is made by joining the encapsulated semiconductor package to another semiconductor chip mounted on the substrate formed external connection terminals and sealing them.